D3206, JANUARY 1989-REVISED APRIL 1989

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

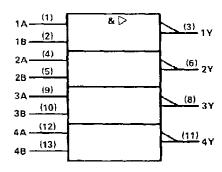
These devices contain four independent 2-input NAND buffer gates. They perform the Boolean functions $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54F37 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F37 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

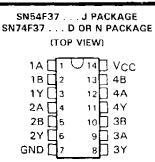
INP	UTS	OUTPUT
Α	В	Y
H	H	L
L	Х	Н
_ x	L	_ н

logic symbol†

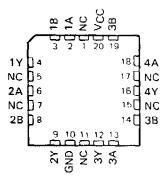


[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

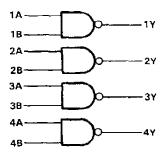


SN54F37 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC	-0.5 V to 7 V
Input voltage†	-0.5 V to 7 V
Input current –	
Voltage applied to any output in the high state	-0.5 V to VCC
Current into any output in the low state	128 mA
Operating free-air temperature range: SN54F37	55°C to 125°C
SN74F37	
Storage temperature range	65°C to 150°C

[†]The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

			SN54F37			SN74F37			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	٧	
VIH	High-level input voltage	2			2			٧	
VIL	Low-level input voltage	,		0.8			0.8	V	
lικ	Input clamp current			- 18			- 18	mΑ	
IOH	High-level output current			- 15			- 15	mA	
lOL	Low-level output current			48			64	mA	
TA	Operating free-air temperature	~ 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN74F37					
PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP	MAX	UNIT
VIK	V _{CC} = 4.5 V, I ₁ = -18 mA		-0.73	- 1.2			-1.2	>
	$V_{CC} = 4.5 \text{ V}, 1_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		
∨он	$V_{CC} = 4.5 \text{ V}, I_{OH} = -15 \text{ mA}$	2			2			٧
	$V_{CC} = 4.75 \text{ V}, I_{OH} = -1 \text{ mA}$				2.7			
2/	1 _{OL} = 48 mA		0.35	0.5		•		ν
VOT .	V _{CC} = 4.5 V I _{OL} = 64 mA					0.40	0.55	
lj.	V _{CC} = 5.5 V, V _I = 7 V			0.1			0.1	mΑ
ін	$V_{CC} = 5.5 \text{ V}, V_{I} = 2.7 \text{ V}$			20			20	μА
իլ .	$V_{CC} = 5.5 \text{ V}, V_1 = 0.5 \text{ V}$			-0.6			-0.6	mA
los [‡]	$V_{CC} = 5.5 \text{ V}, V_{O} = 0$	-100	-	- 225	- 100		- 225	mA
ГССН	$V_{CC} = 5.5 \text{ V}, V_{\parallel} = 0$		3	6		3	6	mA
ICCL	V _{CC} = 5.5 V, V _I = 4.5 V		23	33		23	33	mΑ

switching characteristics (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C			V _{CC} = 4.5 V to 5.5 V. C _L = 50 pF. R _L = 500 Ω. T _A = MIN to MAX [§]				UNIT
				′F37		SN5	4F37	SNZ	4F37	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tpLH	A B	Υ	1.5	3.1	5.5	1	7	1.5	6.5	
^t PHL	AorB		1	2.1	4.5	1	6	1	5	ns

 $^{^{\}dagger}$ All typical values are at VCC = 5 V, TA = 25 °C.

NOTE 1: Load circuits and waveforms are shown in Section 1 of the F Logic Data Book, 1989.



Not more than one output should be shorted at a time and the duration of the short circuit should not exceed one second.

[§]For conditions shown as MIN or MAX, use the appropriate value specified under Recommended Operating Conditions.

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